

This listing of claims will replace all prior versions, and listings, of claims in the application.

### Listing of Claims

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Claims 1-13 (withdrawn)

Claim 14 (currently amended): A chip package structure comprising

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a chip having a bumps formed thereon and a substrate having interconnect points on a metallization thereon, the bumps forming contacts with the interconnect points, wherein each said contact comprises an interconnection layer situated at an interface between the bump and the interconnect point in contact therewith, the layer comprising an alloy of is ~~formed at an interface between the material of each the bump and the material of the interconnect point~~ contact in contact with the bump.

Claim 15 (original): The chip package structure of claim 14 wherein a cured adhesive polymer is situated in a middle region between the bump surface of the chip and the surface of the substrate.

Claim 16 (original): The chip package structure of claim 14 wherein the bump material comprises gold and the interconnect points comprise Sn, and the alloy at the interface comprises a Au/Sn alloy.

Claim 17 (original): The chip package structure of claim 16 wherein the alloy at the interface is a 20:80 Sn:Au alloy.

Claim 18 (new): A chip package structure comprising

a chip having bumps formed thereon and a substrate having interconnect points on a metallization thereon, the bumps forming contacts with the interconnect points, wherein each said contact comprises an alloy of the material of the bump and the material of the interconnect point, the alloy being limited to a layer situated at an interface between the bump and the interconnect point, and

a first cured adhesive polymer forming a spot situated in a middle region between the bump surface of the chip and the surface of the substrate, there being no first cured adhesive polymer at the contacts.

Claim 19 (new): The chip package structure of claim 18 wherein the bump material comprises gold and the interconnect points comprise Sn, and the alloy at the interface comprises a Au/Sn alloy.

Claim 20 (new): The chip package structure of claim 19 wherein the alloy at the interface is a 20:80 Sn:Au alloy.

Claim 21 (new): The chip package structure of claim 18, further comprising a second cured adhesive polymer forming an underfill.

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